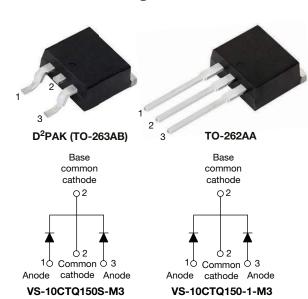
VS-10CTQ150S-M3, VS-10CTQ150-1-M3

Vishay Semiconductors

High Performance Schottky Rectifier, 2 x 5 A



PRIMARY CHARACTERISTICS						
I _{F(AV)} 2 x 5 A						
V _R	150 V					
V _F at I _F	0.93 V					
I _{RM}	7 mA at 125 °C					
T _J max.	175 °C					
E _{AS}	5 mJ					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Common cathode					

FEATURES

- 175 °C T_J operation
- Center tap configuration
- · Low forward voltage drop
- High frequency operation



- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

This center tap Schottky rectifier has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL CHARACTERISTICS VALUES UNITS								
I _{F(AV)}	Rectangular waveform	10	Α					
V _{RRM}		150	V					
I _{FSM}	t _p = 5 μs sine	620	Α					
V _F	5 A _{pk} , T _J = 125 °C (per leg)	0.73	V					
TJ	Range	-55 to +175	°C					

VOLTAGE RATINGS							
PARAMETER SYMBOL VS-10CTQ150S-M3 UNITS UNITS							
Maximum DC reverse voltage	V _R	150	V				
Maximum working peak reverse voltage	V_{RWM}	150	V				



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ABSOLUTE MAXIMUM RATINGS									
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS								
Maximum average per leg		I _{F(AV)} 50 % duty cycle at T _C = 155 °C, rectangular waveform		5	Α				
forward current, see fig. 5 per device	IF(AV)			10					
Maximum peak one cycle non-repetitive		5 μs sine or 3 μs rect. pulse	Following any rated load	620	А				
surge current per leg, see fig. 7	I _{FSM}	10 ms sine or 6 ms rect. pulse	condition and with rated V _{RRM} applied	115					
Non-repetitive avalanche energy per leg E_{AS} $T_J = 25$ °C, $I_{AS} = 1$ A, L = 10 mH		5	mJ						
Repetitive avalanche current per leg	ve avalanche current per leg I_{AR} Current decaying linearly to zero in 1 μs $Frequency limited by T1 maximum V2 = 1.5 x V2 typical$		1	А					

ELECTRICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CO	TEST CONDITIONS					
		5 A	T 05 %C	0.93	V			
Maximum forward voltage drop per leg	V (1)	10 A	T _J = 25 °C	1.10				
See fig. 1	V _{FM} ⁽¹⁾	5 A	T 405.00	0.73				
		10 A	- T _J = 125 °C	0.86				
Maximum reverse leakage current per	I _{RM} ⁽¹⁾	T _J = 25 °C	V Dated V	0.05	- mA			
leg See fig. 2		T _J = 125 °C	V_R = Rated V_R	7				
Threshold voltage	V _{F(TO)}	T Ti		0.468	V			
Forward slope resistance				28	mΩ			
Maximum junction capacitance per leg	C _T	V _R = 5 V _{DC} (test signal range	200	pF				
Typical series inductance per leg	L _S	Measured lead to lead 5 mm	8.0	nH				
Maximum voltage rate of change	dV/dt	Rated V _R	Rated V _B					

Note

 $^{^{(1)}\,}$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER		SYMBOL	SYMBOL TEST CONDITIONS		UNITS				
Maximum junction and st temperature range	orage	T _J , T _{Stg}		-55 to +175	°C				
Maximum thermal resistance, junction to case per leg		Ь	DC operation	3.50					
Maximum thermal resistance, junction to case per package		- R _{thJC}	DC operation	1.75	°C/W				
Typical thermal resistance, case to heatsink (only for TO-220)		R _{thCS}	Mounting surface, smooth and greased	0.50					
Approximate weight				2	g				
Approximate weight				0.07	oz.				
minimum				6 (5)	kgf · cm				
Mounting torque	maximum			12 (10))) (lbf·in)				
Madiandaria			Case style D ² PAK (TO-263AB)	10CTQ1	50S				
Marking device			Case style TO-262AA	10CTQ1	50-1				



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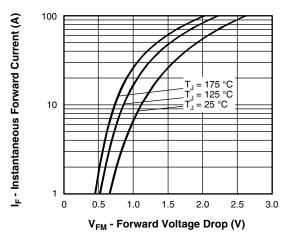


Fig. 1 - Maximum Forward Voltage Drop Characteristics (Per Leg)

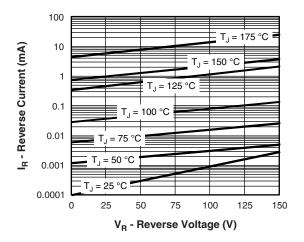


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage (Per Leg)

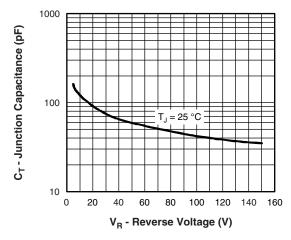


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

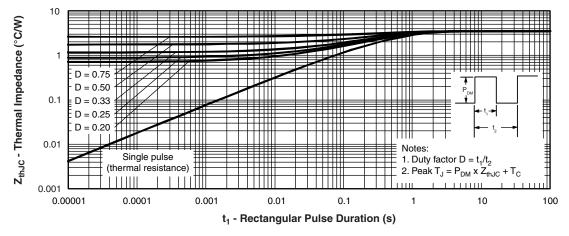


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics (Per Leg)

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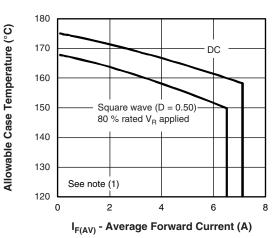


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

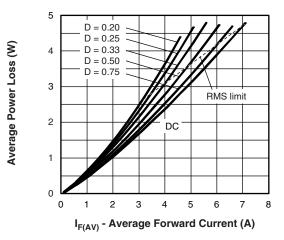


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

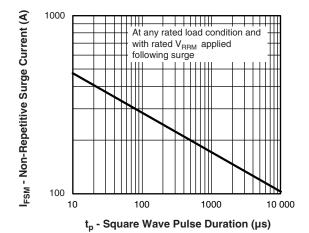


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

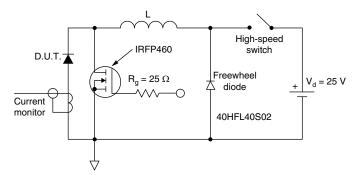


Fig. 8 - Unclamped Inductive Test Circuit

Note

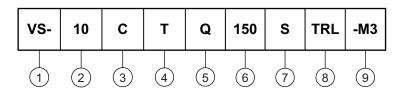
 $^{(1)}$ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC};$ $Pd = forward power loss = I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); $Pd_{REV} = inverse power loss = V_{R1} \times I_R$ (1 - D); I_R at $V_{R1} = 10 \ V$

VS-10CTQ150S-M3, VS-10CTQ150-1-M3

Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Current rating (10 A)

- Circuit configuration: C = common cathode

4 - T = TO-220

5 - Schottky "Q" series

Voltage rating (150 = 150 V)

7 - • S = D^2PAK (TO-263AB)

• -1 = TO-262AA

• None = tube (50 pieces)

• TRL = tape and reel (left oriented - for D²PAK (TO-263AB) only)

• TRR = tape and reel (right oriented - for D²PAK (TO-263AB) only)

9 - -M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION							
VS-10CTQ150S-M3	50	Antistatic plastic tubes					
VS-10CTQ150STRL-M3	800	13" diameter plastic tape and reel					
VS-10CTQ150STRR-M3	800	13" diameter plastic tape and reel					
VS-10CTQ150-1-M3	50	Antistatic plastic tubes					

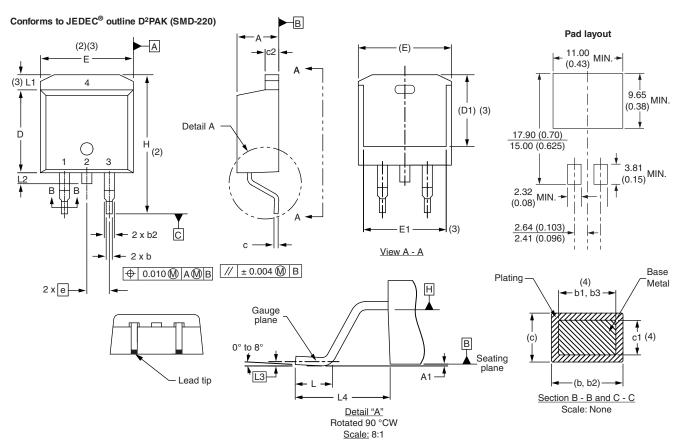
LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
Dimensions	TO-262AA	www.vishay.com/doc?96165				
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Fait marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information		www.vishay.com/doc?96424				



Vishay Semiconductors

D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	INCHES		ES SYMBOL		MILLIM	ETERS	INC	HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOIES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

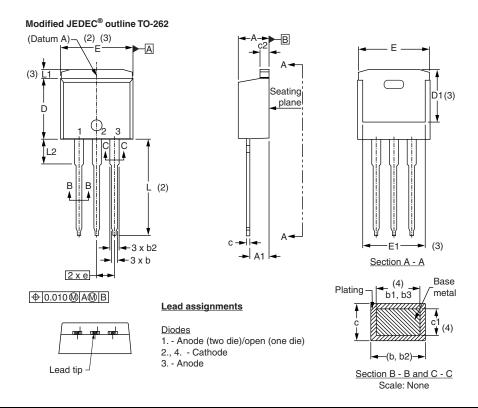
Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

Vishay Semiconductors

TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INC	INCHES		
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	
Α	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.10	0 BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.36	3.71	0.132	0.146		

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

Revision: 11-Jul-2019 1 Document Number: 95419



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Vishay

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